

1.	Record Nr.	UNICAMPANIAVAN0005118
	Titolo	Giuseppe Dossetti : prime prospettive e ipotesi di ricerca / a cura di Giuseppe Alberigo
	Pubbl/distr/stampa	145 p. ; 21 cm
	ISBN	88-15-06741-8
	Edizione	[[Bologna] : Il mulino]
	Descrizione fisica	Con una scelta di scritti di G. Dossetti.
	Disciplina	261.7092
	Soggetti	Dossetti, Giuseppe
	Lingua di pubblicazione	Italiano
	Formato	Materiale a stampa
	Livello bibliografico	Monografia
2.	Record Nr.	UNINA9910299666903321
	Autore	Raiteri Daniele
	Titolo	Circuit Design on Plastic Foils / / by Daniele Raiteri, Eugenio Cantatore, Arthur van Roermund
	Pubbl/distr/stampa	Cham : , : Springer International Publishing : , : Imprint : Springer, , 2015
	ISBN	3-319-11427-1
	Edizione	[1st ed. 2015.]
	Descrizione fisica	1 online resource (138 p.)
	Collana	Analog Circuits and Signal Processing, , 1872-082X
	Disciplina	620 621.381 621.3815
	Soggetti	Electronic circuits Electronics Microelectronics Circuits and Systems Electronic Circuits and Devices Electronics and Microelectronics, Instrumentation
	Lingua di pubblicazione	Inglese
	Formato	Materiale a stampa

Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references.
Nota di contenuto	Introduction -- Applications of large-area electronics on foils -- State of the art in circuit design -- Device modeling and characterization -- Sensor frontend architecture -- Circuit design for analog signal conditioning -- Circuit design for data conversion -- Circuit design for digital processing -- Conclusions.
Sommario/riassunto	This book illustrates a variety of circuit designs on plastic foils and provides all the information needed to undertake successful designs in large-area electronics. The authors demonstrate architectural, circuit, layout, and device solutions and explain the reasons and the creative process behind each. Readers will learn how to keep under control large-area technologies and achieve robust, reliable circuit designs that can face the challenges imposed by low-cost low-temperature high-throughput manufacturing. • Discusses implications of problems associated with large-area electronics and compares them to standard silicon; • Provides the basis for understanding physics and modeling of disordered material; • Includes guidelines to quickly setup the basic CAD tools enabling efficient and reliable designs; • Illustrates practical solutions to cope with hard/soft faults, variability, mismatch, aging and bias stress at architecture, circuit, layout, and device levels.